



**江苏长晶科技股份有限公司**  
JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD.

## 产 品 规 格 书

### SPECIFICATIONS FOR PRODUCT

产品类型 TYPE : SMD3225

产品规格 SPEC : 16MHz/3225/20PF/10PPM

产品型号 P/N : CJ13-160002010B20

日期 DATE : 2022/01/18

核准及签名			部门
R&D APPR. SIGNATURED			DEPT.
拟制	审核	批准	频率器件事业部
ISSUE	CHECK	APPROVAL	
Ivan 2022/01/18	Abbey 2022/01/18	Ken 2022/01/18	

江 苏 长 晶 科 技 股 份 有 限 公 司

JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD.

地址：中国江苏省南京江北新区产业技术研创园江淼路88号腾飞大厦C座13楼

Add: 13Th Floor, C Block, Tengfei Building, No. 88 Jiangmiao Rd. Pukou

District, Nanjing City, Jiangsu Province, China



## SMCE3225 4 pads Crystal Resonator

### CJ13-160002010B20

#### 1. Scope:

- 1.1 This specification applies to the RoHS/SONY compliance quartz crystal unit with a frequency of 16MHz which will be used in crystal oscillator applications.

#### 2. Construction:

- 2.1 Type of Quartz Resonator: SMCE3225 4pads

#### 3. Electrical Characteristics

- |   |                      |
|---|----------------------|
| 3.1 Nominal Frequency(f):                     | 16.000MHz            |
| 3.2 Load Capacitance( $C_L$ ):                | 20pF                 |
| 3.3 Frequency Tolerance( $\Delta f/f$ ):      | $\pm 10$ ppm         |
| 3.4 Frequency Temperature Stability:          | $\pm 20$ ppm         |
| 3.5 Resonance Resistance(ohm):                | 40ohms Max           |
| 3.6 Osc mode:                                 | Fundamental mode     |
| 3.7 Shunt Capacitance( $C_0$ ):               | <2pF                 |
| 3.8 Drive Level( $D_L$ ):                     | <100 $\mu$ W         |
| 3.9 Operating Temperature Range( $T_{OPR}$ ): | -40 to + 85          |
| 3.10 Storage Temperature Range( $T_{STG}$ ):  | -55 to + 125°C       |
| 3.11 Insulation Resistance(IR):               | >500 M ohms          |
| 3.12 Aging( $\Delta f_A$ ):                   | $\pm 3$ ppm per Year |

## 4. Reliability Specifications

This is the quality control and quality assurance and reliability tests performance data for the RoHS/

SONY compliance 16MHz SMCE3225 4pads crystal resonators

related to the specification and approval sheet provided by JSCJ .

Standard test condition (TEMP.: 20±5°C. Relative humidity: 65±20%)

For any discrepancy in GO/NG, test will be done at TEMP.25±2°C, R.H. 65±5%.

NO.	PROCESS	SPECIFICATION	TEST METHOD
4.1	Temperature Cycle (GB/T 2423.22-2002, Method Nb)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	10 cycles from -55°C to 125°C. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.2	Low Temperature Storage (GB/T 2423.1-2001, Method Aa)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Spending 72 hrs at -55°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.3	High Temperature Storage (GB/T 2423.2-2001, Method Ba)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Spending 72 hrs at 125°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.4	Humidity (GB/T 2423.3-2006, Method Cab)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Spending 96 hrs at 40 °C ± 3 °C, with 93 %R.H. Then keep the DUT in dry oven at 40 ± 5 °C for 24 hour. Measurement taken after DUT being left at room temperature for 1 to 2 hours.
4.5	Vibration (GB/T 2423.10-1995, Method Fc)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Apply 0.75mm vibration at sweep frequency 10~500 Hz, 10 cycles in each direction of 3 axis. Measurement taken after 1 hour.
4.6	Shock (GB/T 2423.5-1995, Method Ea)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms. and exhibit no visible damage.	Peak 1000m/s <sup>2</sup> , normal width 6ms half sine wave form, 3.7m/s, 3 perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 1 hour.
4.7	Drop (GB/T 2423.8-1995, Method Ed)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms. and exhibit no visible damage.	Free drop to the steel plate with thickness of 3 mm from 1.00 m heights for 3 times.
4.8	Solderability ( IEC60068-2-58, Test Td:)	Terminals shall be covered more then 95% with solder.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and soldering time for 20s ± 5s at 235°C, peak soldering time for 10s ± 1s between 240 and 250°C. There is no need to do functional test. 8-12X magnifier.
4.9	Terminal Strength (JIS-C-6429 Method 1 & 2 )	No visible damage	Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 1.8kg for at least 60 seconds.
4.10	Resistance to Soldering Heat (IEC60068-2-58, Test Td: Table 4)	Frequency change after test $\pm 5$ ppm. Resonance resistance change after test $\leq 10$ ohms.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and soldering time for 60s max at 235°C, peak soldering time for 20s max at 265°C max. Measurement taken after DUT being left at room temperature for at least 2 hours.
4.11	OTHERS		

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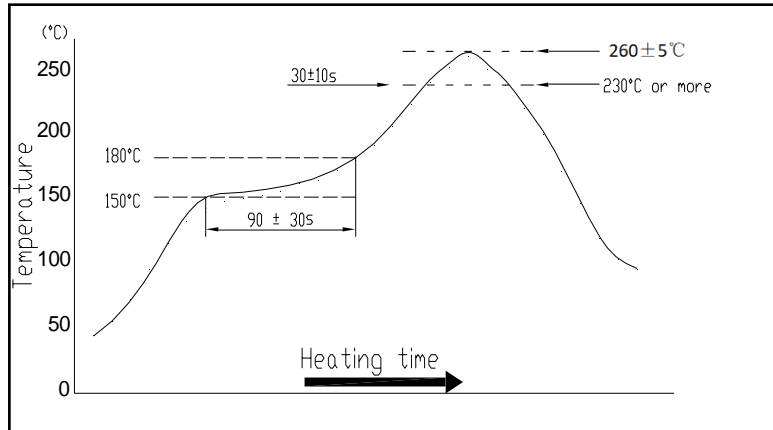
## Recommended Reflow soldering conditon

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### 5. Recommended Reflow soldering condition (SMD)

Solder profile

Peak:  $260 \pm 5^\circ\text{C}$  Soldering zone:  $230^\circ\text{C}$  or more,  $30 \pm 10\text{s}$ . Pre-heating zone 1:  $150 \sim 180^\circ\text{C}$ ,  $90 \pm 30\text{s}$

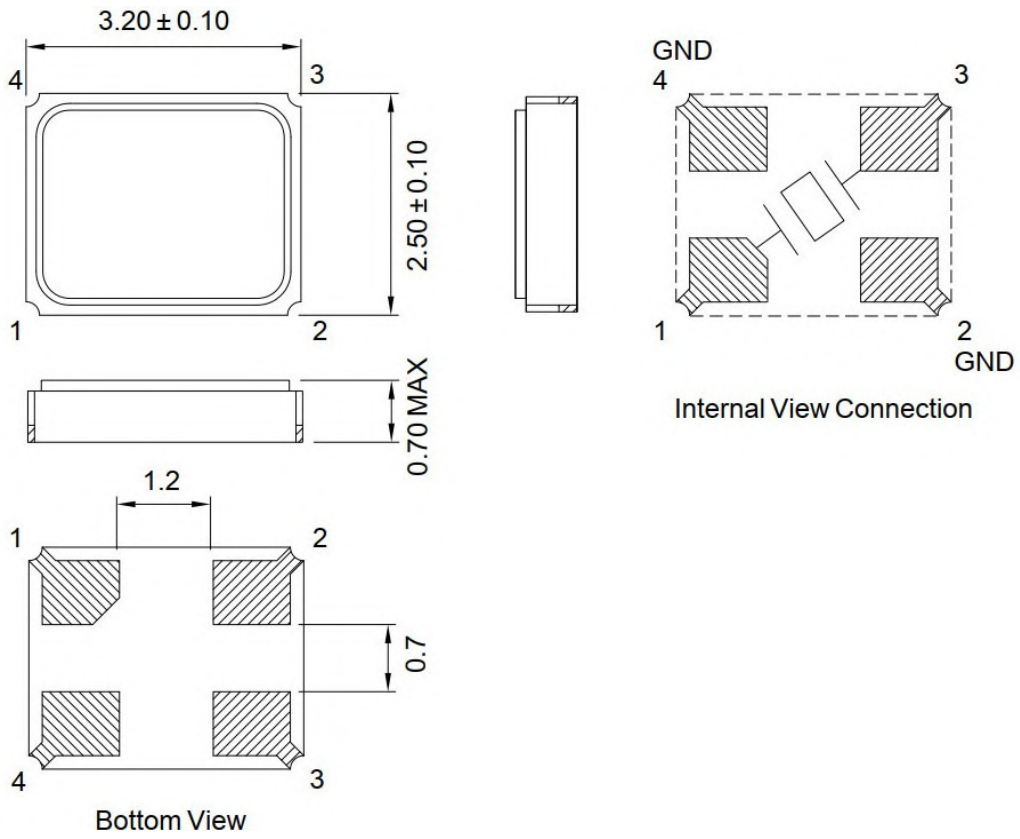


Temperature profile for reflow soldering

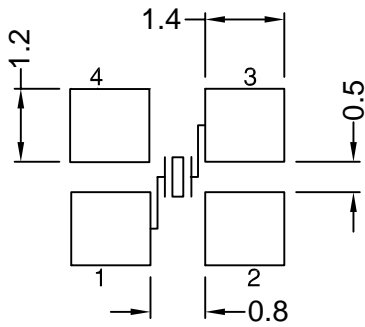
### 6. Soldering iron method

Bit temperature:  $350 \pm 10^\circ\text{C}$  Application time of soldering iron:  $3+1\text{ s}$ . For other procedures, refer to IEC 60068-2-20.

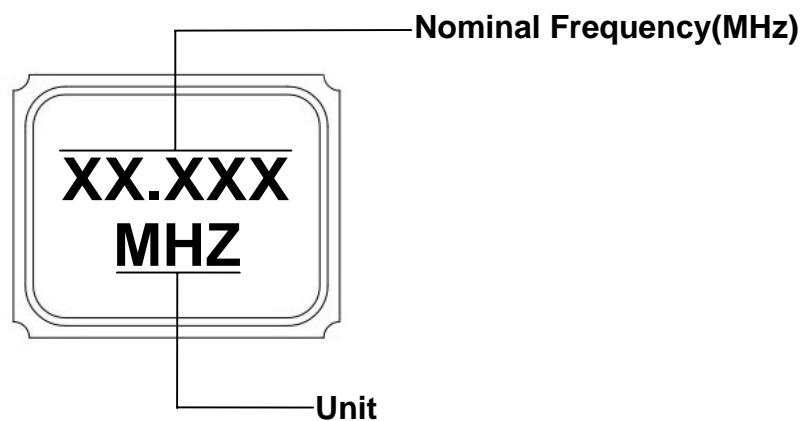
## Package Outline Dimensions



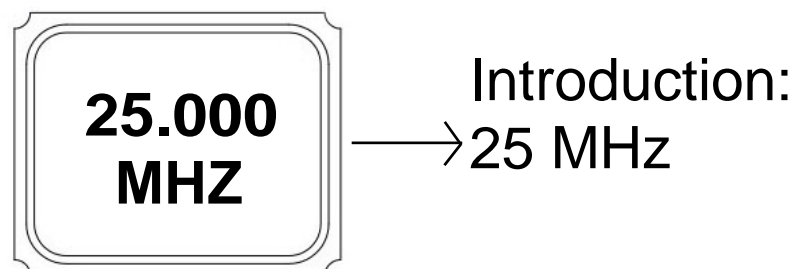
## Suggested Pad Layout



Procedure: Laser



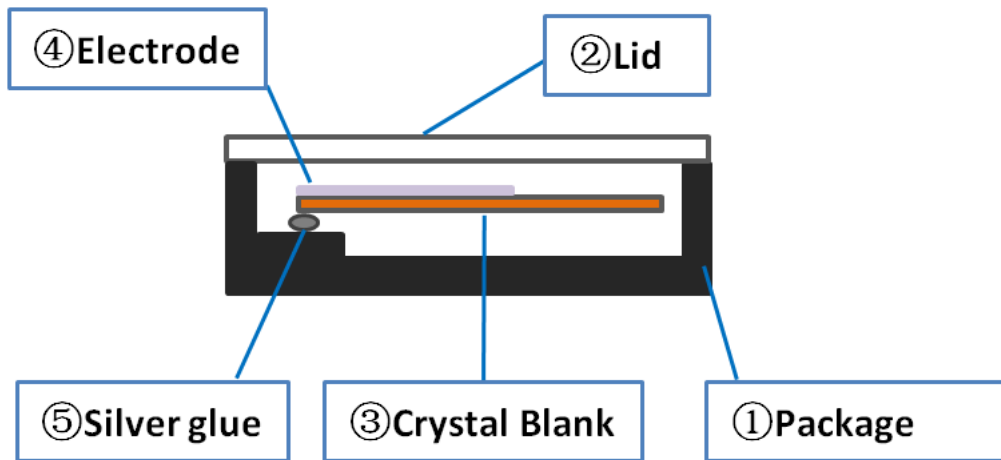
For example:



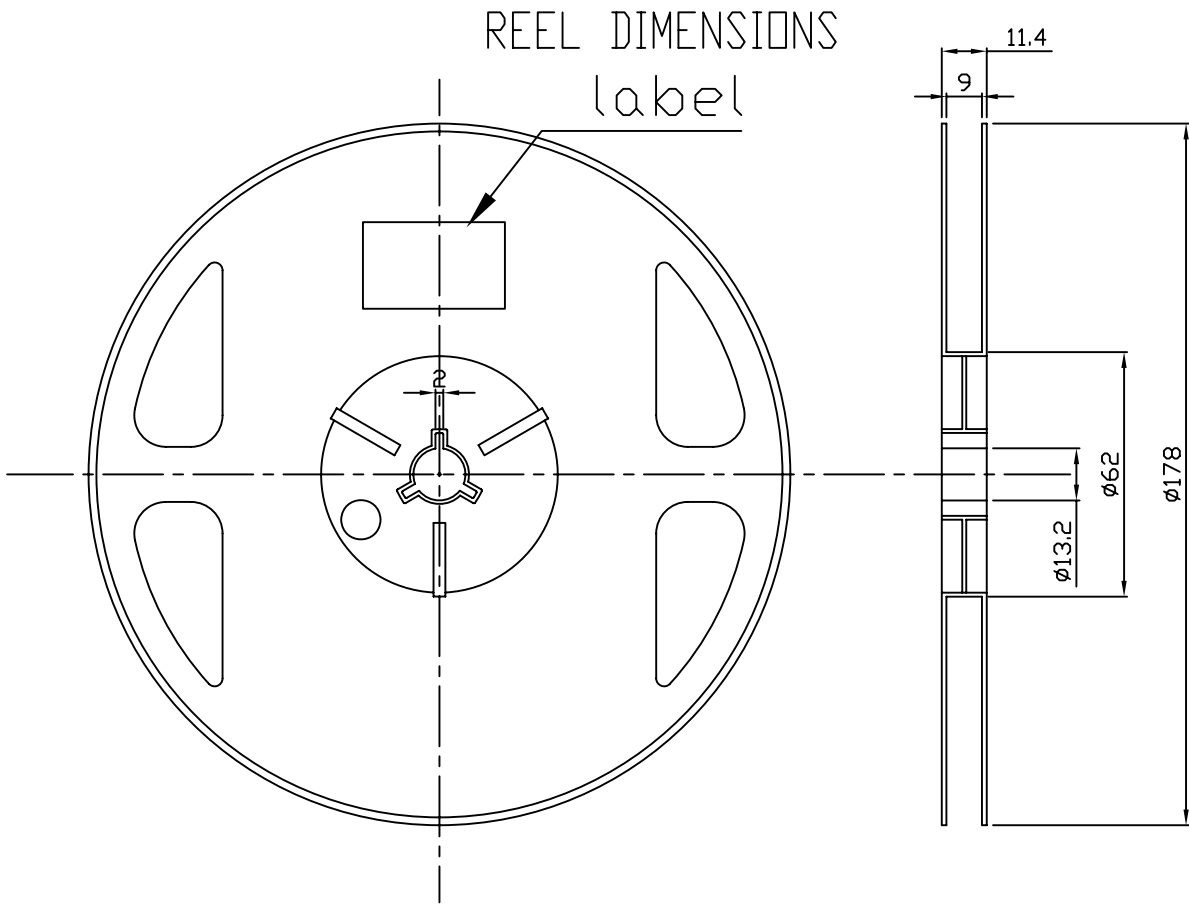
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## Inside Structure

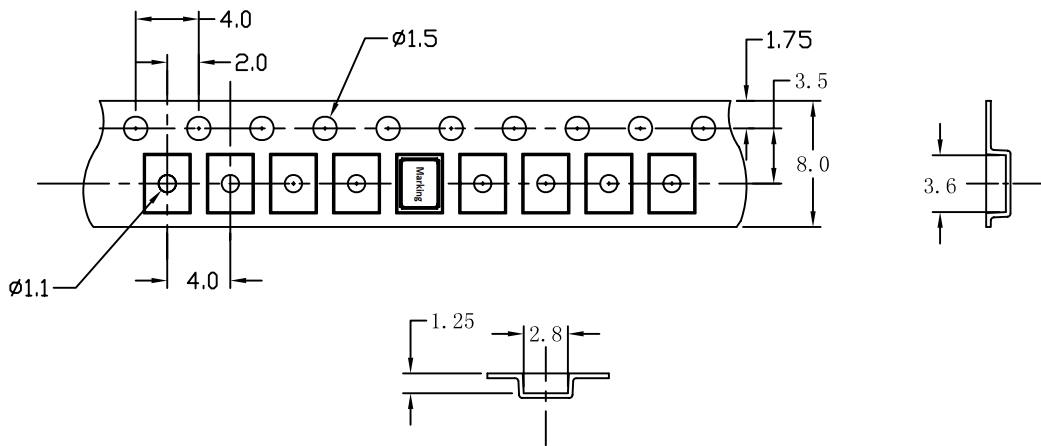
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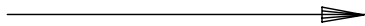
No.	Components	Materials
1	Package	Ceramic( $\text{Al}_2\text{O}_3$ )
2	Lid	KV(Fe/Ni/Co)
3	Crystal blank	$\text{SiO}_2$
4	Electrode	Ag, Cr
5	Silver glue	Ag, $\text{CH}_3\text{OH}$ , $\text{SiO}_2$



EMBOSSED TYPE DIMENSIONS



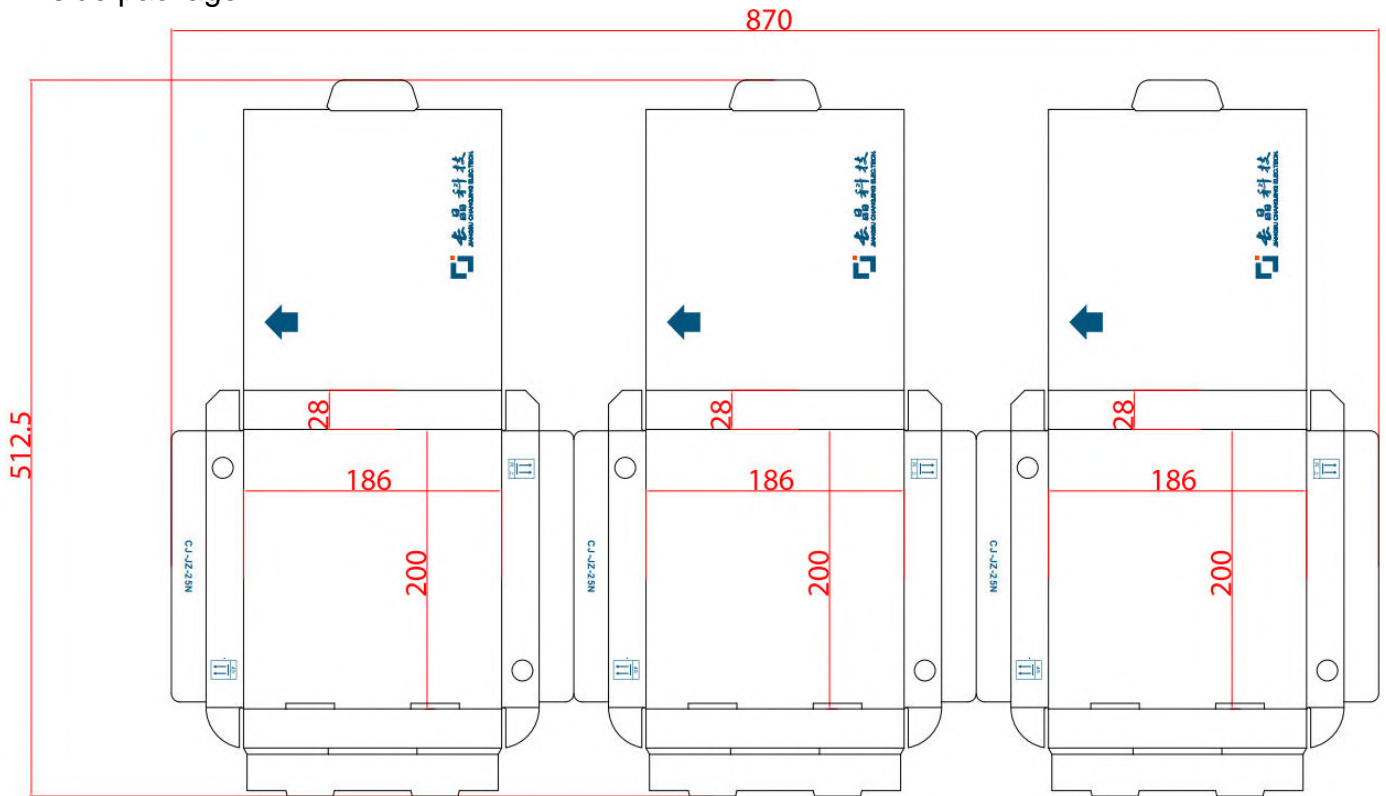
USER FEED DIRECTION



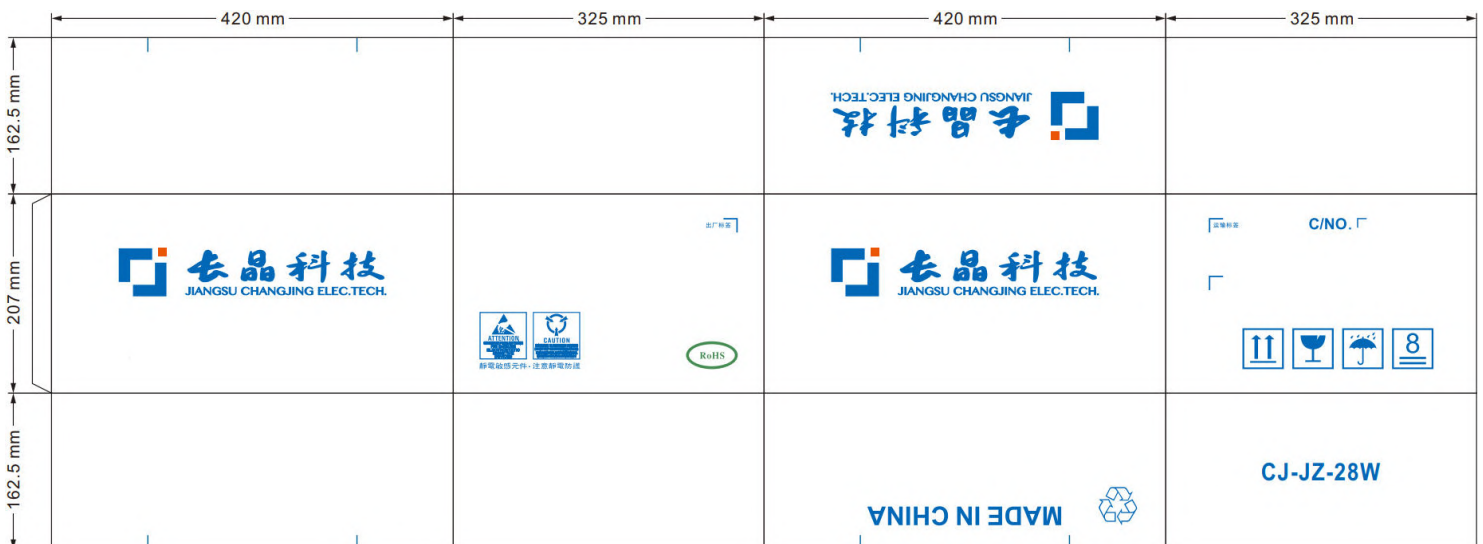


# Package

## Inside package



## Outside package



### NOTICE

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